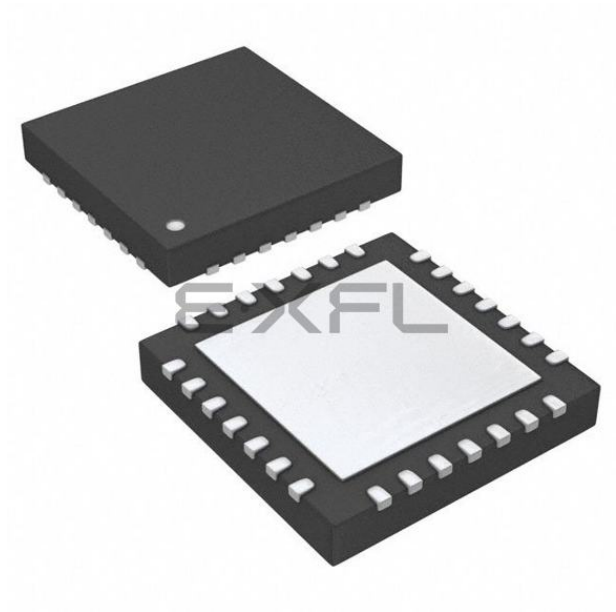


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b/12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08km202-e-ml

Peripheral Features

- High-Current Sink/Source, 18 mA/18 mA All Ports
- Independent Ultra Low-Power, 32 kHz Timer Oscillator
- Up to Two Master Synchronous Serial Ports (MSSPs) with SPI and I^2C™ modes:

  In SPI mode:
  - User-configurable SCKx and SDOx pin outputs
  - Daisy-chaining of SPI slave devices

  In I^2C mode:
  - Serial clock synchronization (clock stretching)
  - Bus collision detection and will arbitrate accordingly
  - Support for 16-bit read/write interface
- Up to Two Enhanced Addressable UARTs:
  - LIN/J2602 bus support (auto-wake-up, Auto-Baud Detect, Break character support)
  - High and low speed (SCI)
  - IrDA® mode (hardware encoder/decoder function)
- Two External Interrupt Pins
- Hardware Real-Time Clock and Calendar (RTCC)
- Configurable Reference Clock Output (REFO)
- Two Configurable Logic Cells (CLC)
- Up to Two Single Output Capture/Compare/PWM (SCCP) modules and up to Three Multiple Output Capture/Compare/PWM (MCCP) modules

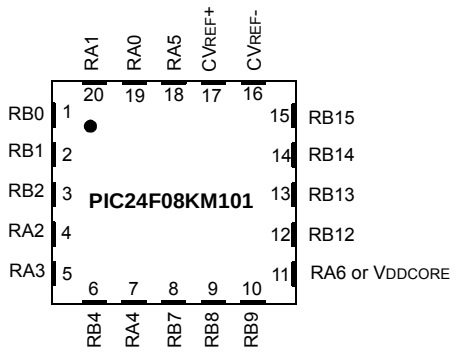
Special Microcontroller Features

- Wide Operating Voltage Range Options:
  - 1.8V to 3.6V (PIC24F devices)
  - 2.0V to 5.0V (PIC24FV devices)
- Selectable Power Management modes:
  - Idle: CPU shuts down, allowing for significant power reduction
  - Sleep: CPU and peripherals shut down for substantial power reduction and fast wake-up
  - Retention Sleep mode: PIC24FV devices can enter Sleep mode, employing the Retention Regulator, further reducing power consumption
  - Doze: CPU can run at a lower frequency than peripherals, a user-programmable feature
  - Alternate Clock modes allow on-the-fly switching to a lower clock speed for selective power reduction
- Fail-Safe Clock Monitor:
  - Detects clock failure and switches to on-chip, low-power RC Oscillator
- Ultra Low-Power Wake-up Pin Provides an External Trigger for Wake from Sleep
- 10,000 Erase/Write Cycle Endurance Flash Program Memory, Typical
- 100,000 Erase/Write Cycle Endurance Data EEPROM, Typical
- Flash and Data EEPROM Data Retention: 20 Years Minimum
- Self-Programmable under Software Control
- Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its Own On-Chip RC Oscillator for Reliable Operation
- On-Chip Regulator for 5V Operation
- Selectable Windowed WDT Feature
- Selectable Oscillator Options including:
  - 4x Phase Locked Loop (PLL)
- 8 MHz (FRC) Internal RC Oscillator:
  - HS/EC, High-Speed Crystal/Resonator Oscillator or External Clock
- In-Circuit Serial Programming™ (ICSP™) and In-Circuit Emulation (ICE) – via Two Pins
- In-Circuit Debugging
- Programmable High/Low-Voltage Detect (HLVD) module
- Programmable Brown-out Reset (BOR):
  - Software enable feature
  - Configurable shutdown in Sleep
  - Auto-configures power mode and sensitivity based on device operating speed
  - LPBOR available for re-arming of the POR

© 2013 Microchip Technology Inc.

Pin Diagrams (Continued)

20-Pin QFN

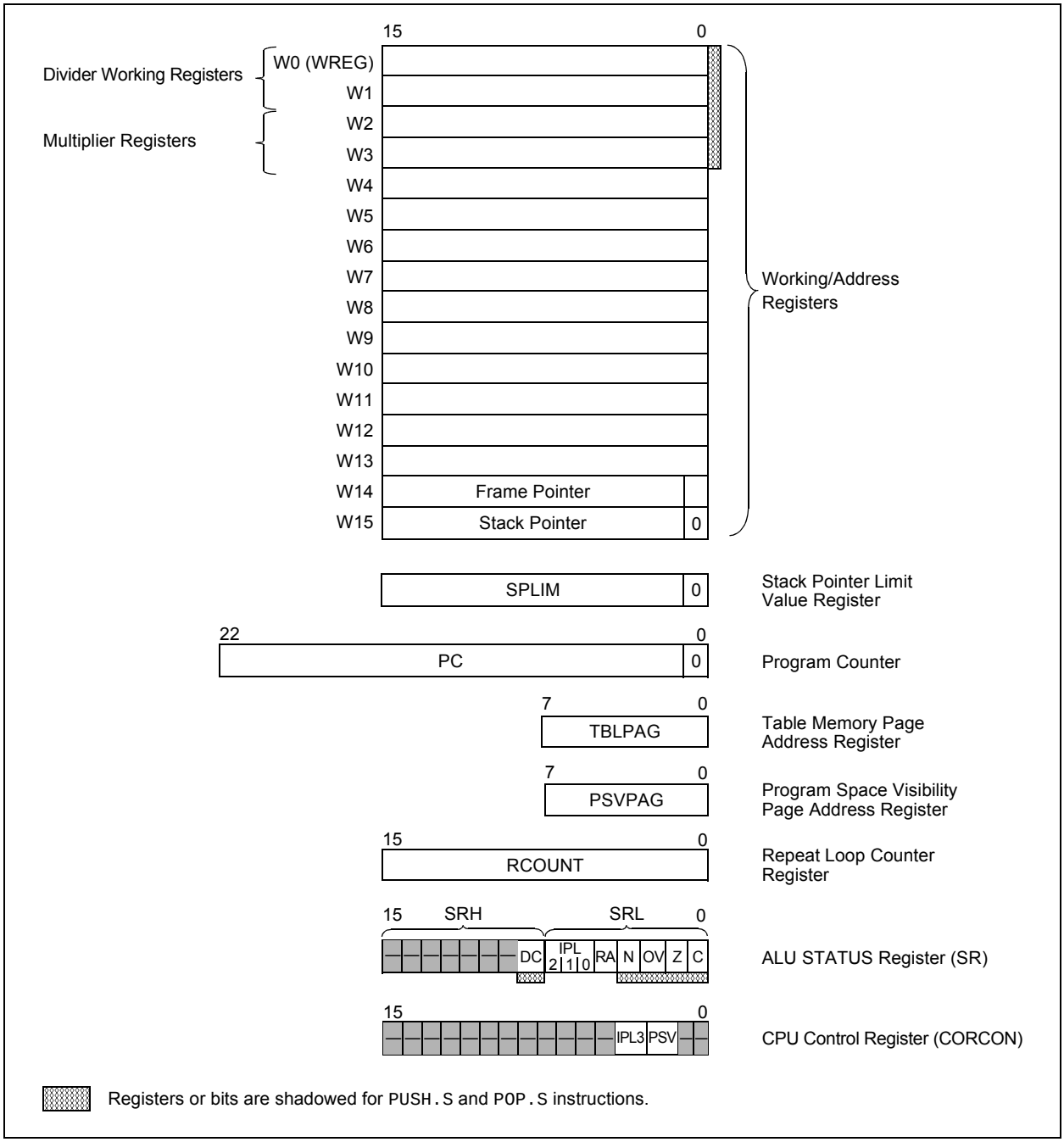


Pin	Pin Features	
	PIC24F08KM101	PIC24FV08KM101
1	PGED1/AN2/CTCMP/ULPWU/C1IND/OC2A/CN4/RB0	
2	PGEC1/AN3/C1INC/CTED12/CN5/RB1	
3	AN4/U1RX/TCKIB/CTED13/CN6/RB2	
4	OSCI/CLKI/AN13/C1INB/CN30/RA2	
5	OSCO/CLKO/AN14/C1INA/CN29/RA3	
6	PGED3/SOSCI/AN15/CLCINA/CN1/RB4	
7	PGEC3/SOSCO/SCLKI/AN16/PWRLCLK/CLCINB/CN0/RA4	
8	AN19/U1TX/CTED1/INT0/CN23/RB7	AN19/U1TX/IC1/OC1A/CTED1/INT0/CN23/RB7
9	AN20/SCL1/$\overline{\text{U1CTS}}$/OC1B/CTED10/CN22/RB8	
10	AN21/SDA1/T1CK/$\overline{\text{U1RTS}}$/U1BCLK/IC2/CLC1O/CTED4/CN21/RB9	
11	IC1/OC1A/INT2/CN8/RA6	VCAP OR VDDCORE
12	AN12/HLVDIN/SCK1/OC1C/CTED2/CN14/RB12	AN12/HLVDIN/SCK1/OC1C/CTED2/INT2/CN14/RB12
13	AN11/SDO1/OCFB/OC1D/CTPLS/CN13/RB13	
14	CVREF/AN10/SDI1/C1OUT/OCFA/CTED5/INT1/CN12/RB14	
15	AN9/REFO/$\overline{\text{SS1}}$/TCKIA/CTED6/CN11/RB15	
16	VSS/AVSS	
17	VDD/AVDD	
18	$\overline{\text{MCLR}}$/VPP/RA5	
19	PGEC2/CVREF+ /VREF+/AN0/CN2/RA0	
20	PGED2/CVREF-/VREF-/AN1/CN3/RA1	

Table of Contents

© 2013 Microchip Technology Inc.

FIGURE 3-2: PROGRAMMER'S MODEL



6.4.3 READING THE DATA EEPROM

To read a word from data EEPROM, the Table Read instruction is used. Since the EEPROM array is only 16 bits wide, only the TBLRDL instruction is needed. The read operation is performed by loading TBLPAG and WREG with the address of the EEPROM location, followed by a TBLRDL instruction.

A typical read sequence, using the Table Pointer management (builtin_tblpage and builtin_tbloffset) and Table Read (builtin_tblrdl) procedures from the C30 compiler library, is provided in Example 6-5.

Program Space Visibility (PSV) can also be used to read locations in the data EEPROM.

EXAMPLE 6-5: READING THE DATA EEPROM USING THE TBLRD COMMAND

```
int __attribute__ ((space(eedata))) eeData = 0x1234;
int data;                                               // Data read from EEPROM
/*-----------------------------------------------------------------------------------------------
The variable eeData must be a Global variable declared outside of any method

the code following this comment can be written inside the method that will execute the read
-----------------------------------------------------------------------------------------------
*/
    unsigned int offset;

    // Set up a pointer to the EEPROM location to be erased
    TBLPAG = __builtin_tblpage(&eeData);                // Initialize EE Data page pointer
    offset = __builtin_tbloffset(&eeData);              // Initizlize lower word of address
    data = __builtin_tblrdl(offset);                    // Write EEPROM data to write latch
```


© 2013 Microchip Technology Inc.

7.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) will have a relatively long start-up time. Therefore, one or more of the following conditions is possible after $\overline{\text{SYSRST}}$ is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer (OST) has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

7.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it will begin to monitor the system clock source when $\overline{\text{SYSRST}}$ is released. If a valid clock source is not available at this time, the device will automatically switch to the FRC Oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine (TSR).

7.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the PIC24F CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset, with the exception of four registers. The Reset value for the Reset Control register, RCON, will depend on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, will depend on the type of Reset and the programmed values of the FNOSCx bits in the Flash Configuration Word (FOSCSEL<2:0>); see Table 7-2. The RCFGCAL and NVMCON registers are only affected by a POR.

7.4 Brown-out Reset (BOR)

The PIC24FXXXXX family devices implement a BOR circuit, which provides the user several configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> Configuration bits (FPOR<6:5,1:0>). There are a total of four BOR configurations, which are provided in Table 7-3.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '00'), any drop of V_{DD} below the set threshold point will reset the device. The chip will remain in BOR until V_{DD} rises above the threshold.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above the threshold. Then, it will keep the chip in Reset for an additional time delay, T_{PWRT}, if V_{DD} drops below the threshold while the Power-up Timer is running. The chip goes back into a BOR and the Power-up Timer will be initialized. Once V_{DD} rises above the threshold, the Power-up Timer will execute the additional time delay.

BOR and the Power-up Timer (PWRT) are independently configured. Enabling the Brown-out Reset does not automatically enable the PWRT.

7.4.1 LOW-POWER BOR (LPBOR)

The Low-Power BOR is an alternate setting for the BOR, designed to consume minimal power. In LPBOR mode, BORV<1:0> (FPOR<6:5>) = 00. The BOR trip point is approximately 2.0V. Due to the low current consumption, the accuracy of the LPBOR mode can vary.

Unlike the other BOR modes, LPBOR mode will not cause a device Reset when V_{DD} drops below the trip point. Instead, it re-arms the POR circuit to ensure that the device will reset properly in the event that V_{DD} continues to drop below the minimum operating voltage.

The device will continue to execute code when V_{DD} is below the level of the LPBOR trip point. A device that requires falling edge BOR protection to prevent code from improperly executing should use one of the other BOR voltage settings.

REGISTER 8-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
NSTDIS	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0
—	—	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14-5 **Unimplemented:** Read as '0'

bit 4 **MATHERR:** Arithmetic Error Trap Status bit
1 = Overflow trap has occurred
0 = Overflow trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

bit 2 **STKERR:** Stack Error Trap Status bit
1 = Stack error trap has occurred
0 = Stack error trap has not occurred

bit 1 **OSCFAIL:** Oscillator Failure Trap Status bit
1 = Oscillator failure trap has occurred
0 = Oscillator failure trap has not occurred

bit 0 **Unimplemented:** Read as '0'

9.0 OSCILLATOR CONFIGURATION

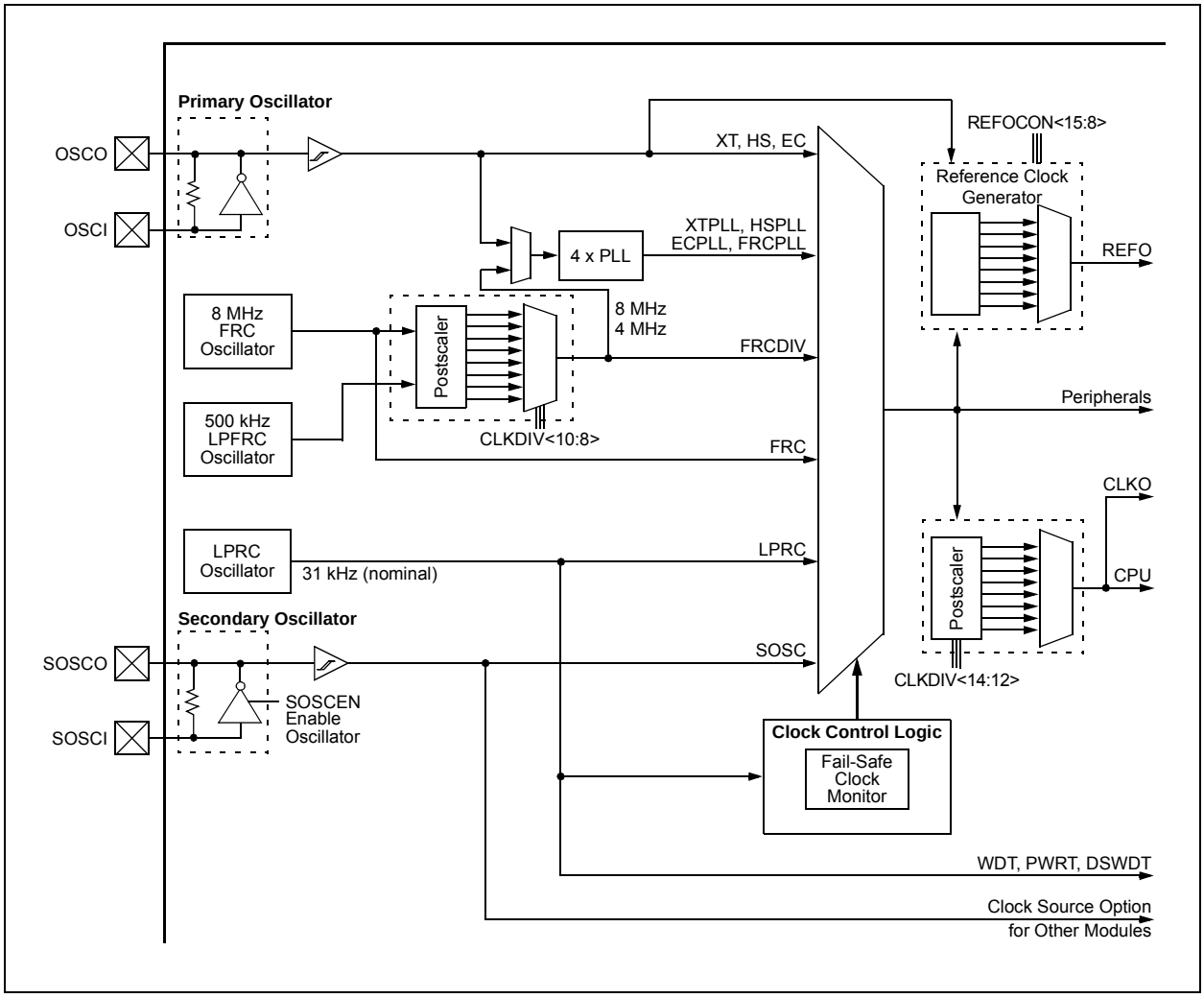
Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on oscillator configuration, refer to the *"PIC24F Family Reference Manual"*, **"Oscillator with 500 kHz Low-Power FRC"** (DS39726).

The oscillator system for the PIC24FV16KM204 family of devices has the following features:

- A total of five external and internal oscillator options as clock sources, providing 11 different clock modes.
- On-chip 4x Phase Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources.
- Software-controllable switching between various clock sources.
- Software-controllable postscaler for selective clocking of CPU for system power savings.
- System frequency range declaration bits for External Clock (EC) mode. When using an EC source, the current consumption is reduced by setting the declaration bits to the expected frequency range.
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown.

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: PIC24FXXXXX FAMILY CLOCK DIAGRAM



REGISTER 11-2: ANSB: PORTB ANALOG SELECTION REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	U-0	U-0	R/W-1	R/W-1
ANSB15	ANSB14	ANSB13	ANSB12	—	—	ANSB9	ANSB8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
ANSB7	ANSB6(1)	ANSB5(1)	ANSB4	ANSB3(1)	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **ANSB<15:12>:** Analog Select Control bits
1 = Digital input buffer is not active (use for analog input)
0 = Digital input buffer is active

bit 11-10 **Unimplemented:** Read as '0'

bit 9-0 **ANSB<9:0>:** Analog Select Control bits(1)
1 = Digital input buffer is not active (use for analog input)
0 = Digital input buffer is active

Note 1: The ANSB<6:5,3> bits are not available on 20-pin devices.

REGISTER 11-3: ANSC: PORTC ANALOG SELECTION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	ANSC2(1,2)	ANSC1(1,2)	ANSC0(1,2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as '0'

bit 2-0 **ANSC<2:0>:** Analog Select Control bits(1,2)
1 = Digital input buffer is not active (use for analog input)
0 = Digital input buffer is active

Note 1: These bits are not implemented in 20-pin devices.
2: These bits are not implemented in 28-pin devices.

REGISTER 13-6: CCPxCON3H: CCPx CONTROL 3 HIGH REGISTERS

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
OETRIG	OSCNT2	OSCNT1	OSCNT0	—	OUTM2(1)	OUTM1(1)	OUTM0(1)
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	POLACE	POLBDF(1)	PSSACE1	PSSACE0	PSSBDF1(1)	PSSBDF0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **OETRIG:** CCPx Dead-Time Select bit
1 = For Triggered mode (TRIGEN = 1): Module does not drive enabled output pins until triggered
0 = Normal output pin operation

bit 14-12 **OSCNT<2:0>:** One-Shot Event Count bits
111 = Extend one-shot event by 7 time base periods (8 time base periods total)
110 = Extend one-shot event by 6 time base periods (7 time base periods total)
101 = Extend one-shot event by 5 time base periods (6 time base periods total)
100 = Extend one-shot event by 4 time base periods (5 time base periods total)
011 = Extend one-shot event by 3 time base periods (4 time base periods total)
010 = Extend one-shot event by 2 time base periods (3 time base periods total)
001 = Extend one-shot event by 1 time base period (2 time base periods total)
000 = Do not extend one-shot Trigger event

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **OUTM<2:0>:** PWMx Output Mode Control bits(1)
111 = Reserved
110 = Output Scan mode
101 = Brush DC Output mode, forward
100 = Brush DC Output mode, reverse
011 = Reserved
010 = Half-Bridge Output mode
001 = Push-Pull Output mode
000 = Steerable Single Output mode

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **POLACE:** CCPx Output Pins, OCxA, OCxC and OCxE, Polarity Control bit
1 = Output pin polarity is active-low
0 = Output pin polarity is active-high

bit 4 **POLBDF:** CCPx Output Pins, OCxB, OCxD and OCxF, Polarity Control bit(1)
1 = Output pin polarity is active-low
0 = Output pin polarity is active-high

bit 3-2 **PSSACE<1:0>:** PWMx Output Pins, OCxA, OCxC and OCxE, Shutdown State Control bits
11 = Pins are driven active when a shutdown event occurs
10 = Pins are driven inactive when a shutdown event occurs
0x = Pins are tri-stated when a shutdown event occurs

bit 1-0 **PSSBDF<1:0>:** PWMx Output Pins, OCxB, OCxD, and OCxF, Shutdown State Control bits(1)
11 = Pins are driven active when a shutdown event occurs
10 = Pins are driven inactive when a shutdown event occurs
0x = Pins are in a high-impedance state when a shutdown event occurs

Note 1: These bits are implemented in MCCPx modules only.

REGISTER 19-5: AD1CHS: A/D SAMPLE SELECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB2	CH0NB1	CH0NB0	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA2	CH0NA1	CH0NA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **CH0NB<2:0>:** Sample B Channel 0 Negative Input Select bits
111 = AN6(1)
110 = AN5(2)
101 = AN4
100 = AN3
011 = AN2
010 = AN1
001 = AN0
000 = AVSS

bit 12-8 **CH0SB<4:0>:** S/H Amplifier Positive Input Select for MUX B Multiplexer Setting bits
11111 = Unimplemented, do not use
11110 = AVDD(3)
11101 = AVSS(3)
11100 = Upper guardband rail (0.785 * VDD)
11011 = Lower guardband rail (0.215 * VDD)
11010 = Internal Band Gap Reference (VBG)(3)
11000-11001 = Unimplemented, do not use
10001 = No channels are connected, all inputs are floating (used for CTMU)
10111 = No channels are connected, all inputs are floating (used for CTMU)
10110 = No channels are connected, all inputs are floating (used for CTMU temperature sensor input); does not require the corresponding CTMEN22 (AD1CTMENH<6>) bit)
10101 = Channel 0 positive input is AN21
10100 = Channel 0 positive input is AN20
10011 = Channel 0 positive input is AN19
10010 = Channel 0 positive input is AN18(2)
10001 = Channel 0 positive input is AN17(2)
•
•
•
01001 = Channel 0 positive input is AN9
01000 = Channel 0 positive input is AN8(1)
00111 = Channel 0 positive input is AN7(1)
00110 = Channel 0 positive input is AN6(1)
00101 = Channel 0 positive input is AN5(2)
00100 = Channel 0 positive input is AN4
00011 = Channel 0 positive input is AN3
00010 = Channel 0 positive input is AN2
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

Note 1: This is implemented on 44-pin devices only.
2: This is implemented on 28-pin and 44-pin devices only.
3: The band gap value used for this input is 2x or 4x the internal VBG, which is selected when PVCFG<1:0> = 1x.

© 2013 Microchip Technology Inc.

REGISTER 19-7: AD1CHITL: A/D SCAN COMPARE HIT REGISTER (LOW WORD)(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CHH15	CHH14	CHH13	CHH12	CHH11	CHH10	CHH9	CHH8(2,3)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CHH7(2,3)	CHH6(2,3)	CHH5(2)	CHH4	CHH3	CHH2	CHH1	CHH0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **CHH<15:0>:** A/D Compare Hit bits(2,3)

If CM<1:0> = 11:
1 = A/D Result Buffer x has been written with data or a match has occurred
0 = A/D Result Buffer x has not been written with data

For All Other Values of CM<1:0>:
1 = A match has occurred on A/D Result Channel x
0 = No match has occurred on A/D Result Channel x

Note 1: Unimplemented channels are read as '0'.
2: The CHH<8:5> bits are not implemented in 20-pin devices.
3: The CHH<8:6> bits are not implemented in 28-pin devices.

© 2013 Microchip Technology Inc.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

If the WDT is enabled in hardware (FWDTEN<1:0> = 11), it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3:2>) will need to be cleared in software after the device wakes up.

The WDT Flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

Note:	The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

25.3.1 WINDOWED OPERATION

The Watchdog Timer has an optional Fixed Window mode of operation. In this Windowed mode, CLRWDT instructions can only reset the WDT during the last 1/4 of the programmed WDT period. A CLRWDT instruction executed before that window causes a WDT Reset, similar to a WDT time-out.

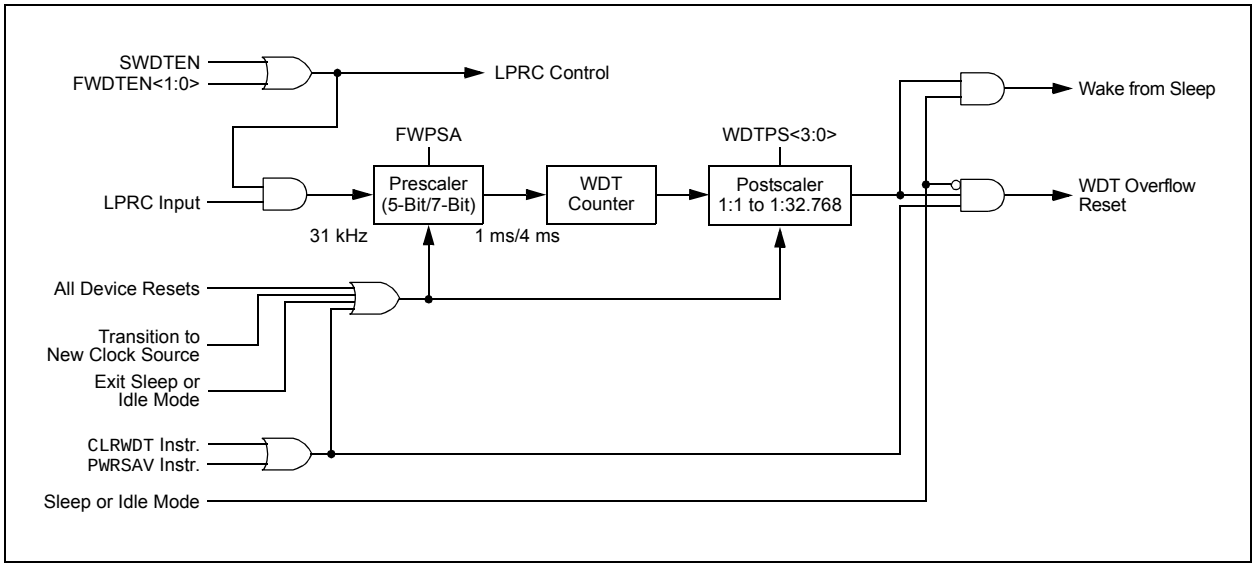
Windowed WDT mode is enabled by programming the Configuration bit, WINDIS (FWDT<6>), to '0'.

25.3.2 CONTROL REGISTER

The WDT is enabled or disabled by the FWDTEN<1:0> Configuration bits. When both of the FWDTEN<1:0> Configuration bits are set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN<1:0> Configuration bits have been programmed to '10'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user to enable the WDT for critical code segments, and disable the WDT during non-critical segments, for maximum power savings. When the FWDTEN<1:0> bits are set to '01', the WDT is only enabled in Run and Idle modes, and is disabled in Sleep. Software control of the SWDTEN bit (RCON<5>) is disabled with this setting.

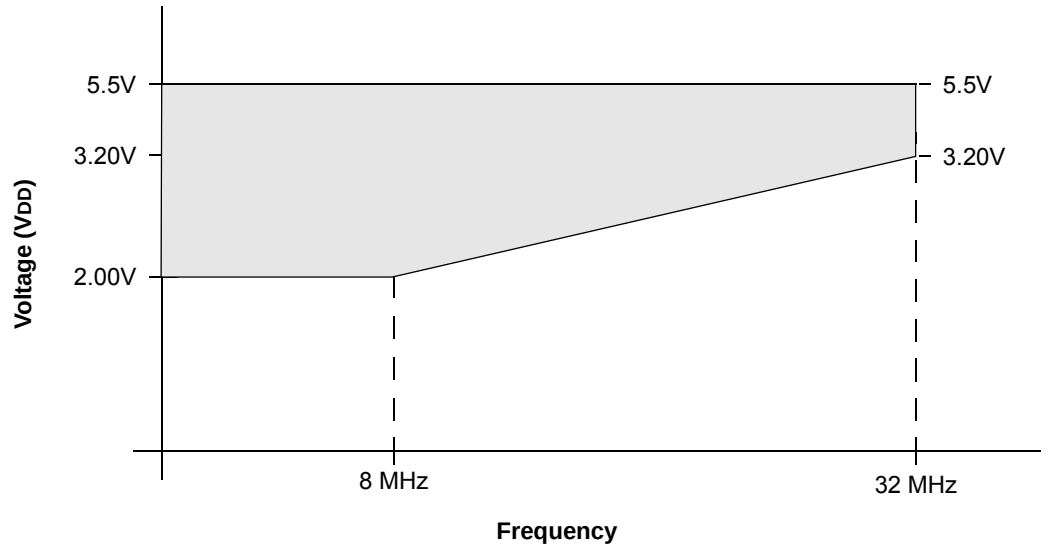
FIGURE 25-2: WDT BLOCK DIAGRAM



© 2013 Microchip Technology Inc.

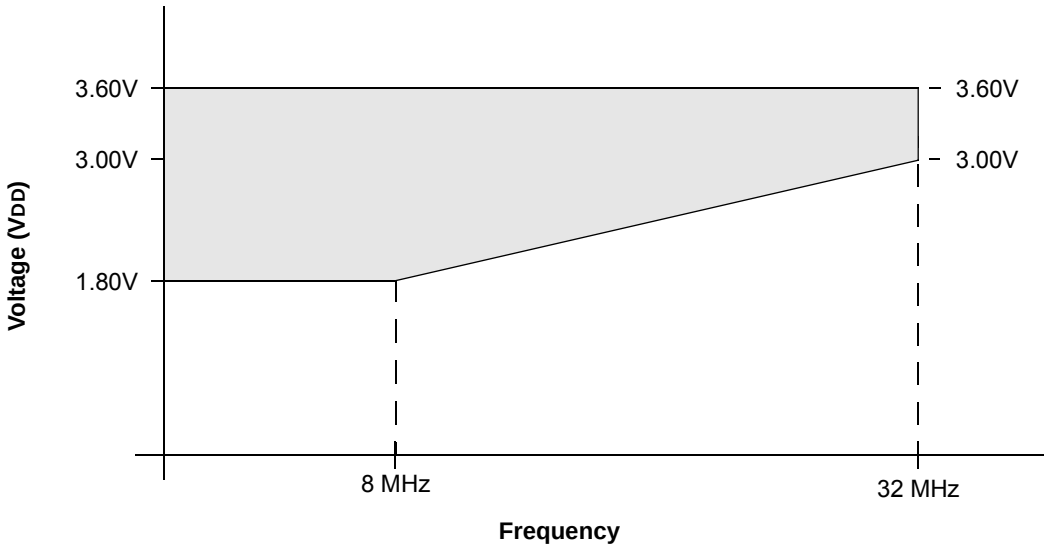
27.1 DC Characteristics

FIGURE 27-1: PIC24FV16KM204 FAMILY VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



Note: For frequencies between 8 MHz and 32 MHz, FMAX = 20 MHz * (VDD – 2.0) + 8 MHz.

FIGURE 27-2: PIC24F16KM204 FAMILY VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



Note: For frequencies between 8 MHz and 32 MHz, FMAX = 20 MHz * (VDD – 1.8) + 8 MHz.

© 2013 Microchip Technology Inc.

TABLE 27-1: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+125	°C
Power Dissipation Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 27-2: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 20-Pin PDIP	θ_{JA}	62.4	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SSOP	θ_{JA}	108	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SOIC	θ_{JA}	75	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	80.2	—	°C/W	**1**
Package Thermal Resistance, 20-Pin QFN	θ_{JA}	43	—	°C/W	**1**
Package Thermal Resistance, 28-Pin QFN	θ_{JA}	32	—	°C/W	**1**
Package Thermal Resistance, 44-Pin QFN	θ_{JA}	29	—	°C/W	**1**
Package Thermal Resistance, 44-Pin TQFP	θ_{JA}	40	—	°C/W	**1**
Package Thermal Resistance, 48-Pin UQFN	θ_{JA}	41	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-$_{JA}$ (θ_{JA}) numbers are achieved by package simulations.

TABLE 27-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KMXXX)** **2.0V to 5.5V (PIC24FV16KMXXX)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DC10	V_{DD}	**Supply Voltage**	1.8	—	3.6	V	For PIC24F devices
			2.0	—	5.5	V	For PIC24FV devices
DC12	V_{DR}	**RAM Data Retention Voltage(2)**	1.6	—	—	V	For PIC24F devices
			1.8	—	—	V	For PIC24FV devices
DC16	V_{POR}	**V_{DD} Start Voltage** to Ensure Internal Power-on Reset Signal	V_{SS}	—	0.7	V	
DC17	SV_{DD}	**V_{DD} Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 0.1s 0-2.5V in 60 ms

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This is the limit to which V_{DD} can be lowered without losing RAM data.

© 2013 Microchip Technology Inc.

TABLE 27-4: HIGH/LOW-VOLTAGE DETECT CHARACTERISTICS

Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) **2.0V to 5.5V (PIC24FV16KM204)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended								
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
DC18	VHLVD	HLVD Voltage on VDD Transition	HLVDL<3:0> = 0000(2)	—	—	1.90	V	
			HLVDL<3:0> = 0001	1.88	—	2.13	V	
			HLVDL<3:0> = 0010	2.09	—	2.35	V	
			HLVDL<3:0> = 0011	2.25	—	2.53	V	
			HLVDL<3:0> = 0100	2.35	—	2.62	V	
			HLVDL<3:0> = 0101	2.55	—	2.84	V	
			HLVDL<3:0> = 0110	2.80	—	3.10	V	
			HLVDL<3:0> = 0111	2.95	—	3.25	V	
			HLVDL<3:0> = 1000	3.09	—	3.41	V	
			HLVDL<3:0> = 1001	3.27	—	3.59	V	
			HLVDL<3:0> = 1010(1)	3.46	—	3.79	V	
			HLVDL<3:0> = 1011(1)	3.62	—	4.01	V	
			HLVDL<3:0> = 1100(1)	3.91	—	4.26	V	
			HLVDL<3:0> = 1101(1)	4.18	—	4.55	V	
			HLVDL<3:0> = 1110(1)	4.49	—	4.87	V	

Note 1: These trip points should not be used on PIC24FXXKMXXX devices.

2: This trip point should not be used on PIC24FVXXKMXXX devices.

TABLE 27-5: BOR TRIP POINTS

Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) **2.0V to 5.5V (PIC24FV16KM204)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended								
Param No.	**Sym**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
DC15		BOR Hysteresis		—	5	—	mV	
DC19		BOR Voltage on VDD Transition	BORV<1:0> = 00	—	—	—	—	Valid for LPBOR (**Note 1)**
			BORV<1:0> = 01	2.90	3	3.38	V	
			BORV<1:0> = 10	2.53	2.7	3.07	V	
			BORV<1:0> = 11	1.75	1.85	2.05	V	**(Note 2)**
			BORV<1:0> = 11	1.95	2.05	2.16	V	**(Note 3)**

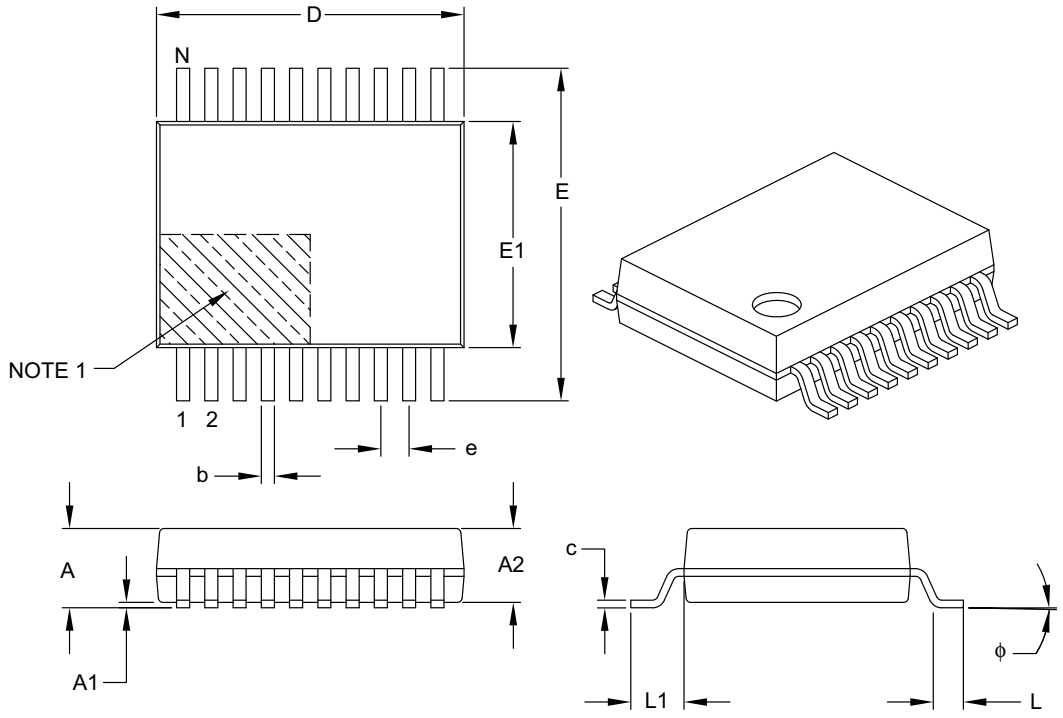
Note 1: LPBOR re-arms the POR circuit but does not cause a BOR.

2: This is valid for PIC24F (3.3V) devices.

3: This is valid for PIC24FV (5V) devices.

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

NOTES:

© 2013 Microchip Technology Inc.

APPENDIX A: REVISION HISTORY

Revision A (February 2013)

Original data sheet for the PIC24FV16KM204 family of devices.

Revision B (July 2013)

Updates all references to PGCx and PGDx pin functions throughout the document to PGECx and PGEDx.

Updates **Section 4.0 "Memory Organization"** to change bit 12 in the following registers to reserved ("r" designation):

- CCP1CON1L (Table 4-8)
- CCP2CON1L (Table 4-9)
- CCP3CON1L (Table 4-10)
- CCP4CON1L (Table 4-11)
- CCP5CON1L (Table 4-12)

Updates **Section 13.0 "Capture/Compare/PWM/ Timer Modules (MCCP and SCCP)"**:

- Replaces bit 12 of CCPxCON1L (CCPSLP) and its description with a reserved bit
- Removes references to asynchronous operation in Sleep mode (and in other occurrences throughout the document)
- Modifies **Section 13.1 "Time Base Generator"** to add synchronous operation limitations; adds Table 13-1 to list valid clock options for all operating modes
- Removes the system clock as a time base input option
- Removes external input sources, comparators and CTMU as synchronization sources in Table 13-6; clarifies that other selected sources must be synchronous

Removes the input buffer from the band gap reference input in Figure 20-1.

Adds BUFCON0 register description (Register 20-2) to **Section 20.0 "8-Bit Digital-to-Analog Converter (DAC)"**.

Changes references to internal band gap voltages (V_{BG}, $V_{BG}/2$ and BGBUF0) in **Section 20.0 "8-Bit Digital-to-Analog Converter (DAC)"** and **Section 22.0 "Comparator Module"** to BGBUF1.

Adds minimum V_{DD} conditions for V_{BG} specification in Table 27-15 (Internal Voltage Regulator Specifications).

Other minor typographical corrections throughout the document.

NOTES:

© 2013 Microchip Technology Inc.